#### **Electrical characteristics** 1

#### Absolute ratings (T<sub>amb</sub> = 25 °C) Table 1.

Symbol	Parameter	Value	Unit
Тj	junction temperature	125	°C
T <sub>op</sub>	Operating temperature range	-40 to +85	°C
T <sub>stg</sub>	Storage temperature range	-55 to 150	°C

#### Electrical characteristics (T<sub>amb</sub> = 25 °C) Table 2.

Symbol	Parameters	I GC			
$V_{BR}$	Breakdown voltage		IPP ···		
I <sub>RM</sub>	Leakage current @ V <sub>RM</sub>	d			
V <sub>RM</sub>	Stand-off voltage				
V <sub>CL</sub>	Clamping voltage			ע עריי	
R <sub>d</sub>	Dynamic impedance			RVCL	
I <sub>PP</sub>	Peak pulse current				
R <sub>I/O</sub>	Series resistance between input and output				
C <sub>line</sub>	Input capacitance per line	- 1			
C <sub>line</sub> Symbol		Min.	Typ.	Max.	Unit
	Input capacitance per line	-   Min. 14	<b>Typ.</b>	Max.	Unit V
Symbol	Input capacitance per line Test conditions			<b>Max.</b>	
Symbol V <sub>BR</sub>	Input capacitance per line Test conditions				V



# Figure 3. Attenuation measurement and Aplac simulation





## Figure 4. Analog crosstalk measurements



Figure 6. ESD response to IEC61000-4-2 (-15 kV air discharge) on one input V(in) and on one output V(out)



Figure 7. ESD response to IEC61000-4-2 (+15 kV air discharge) on one input V(in) and on one output V(out)

Figure 8. Line capacitance versus applied voltage



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#### **Application information** 2





## Figure 10. Aplac parameters

	В	3V = 7	Model D01-int BV = 7 CJO = Cz_int	Model D01-gnd BV = 7 CJO = Cz_gnd	Ls 400pH Rs 100m
	1E 14 15 15 N	BV = 1u KF = 1000 S = 10f SR = 100p I = 1	IBV = 1u		R_470R 482.6 Cz_ext 8.73pF Rs_ext 850m Cz_int 2.9pF Rs_int 850m Cz_gnd 215.61pF
ole	V V	′J = 0.6	RS = Rs_int VJ = 0.6 TT = 50n	$RS = Rs_gnd$ VJ = 0.6 TT = 50n	Rs_gnd 470m Rgnd 10m Lgnd 48pH
5050					Cgnd 0.15pF Cox 3.05pF Rsubump 200m



## **3** Ordering information scheme





# 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK<sup>®</sup> is an ST trademark.



## Figure 12. Package dimensions



# Figure 13. Footprint Figure 14. Marking Copper pad Diameter: Dot, ST logo 250 µm recommended, 300 µm max amanufacturing location Solder stencil opening: 330 µm ww = waek)



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# Ordering information

## Table 3. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
EMIF02-MIC02F2	FJ	Flip Chip	2.3 mg	5000	Tape and reel 7"

Note:

More information is available in the application notes: AN1235:"Flip Chip: Package description and recommendations for use" AN1751: "EMI filters: Recommendations and measurements"



# 6 Revision history

### Table 4.Document revision history

	Date	Revision	Changes
	12-Oct-2004	1	Initial release.
	11-Jan-2006	2	ECOPACK statement added. Die dimensions modified in <i>Figure 12</i> . and first page. Typographical errors corrected.
	17-Apr-2008	3	Updated ECOPACK statement. Updated <i>Figure 11</i> , <i>Figure 12</i> and <i>Figure 15</i> . Reformatted to current standards.
	26-May-2011	4	Updated C <sub>line</sub> values in <i>Table 2</i> .
obsole	stepto	ductl	Updated C <sub>line</sub> values in Table 2.



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